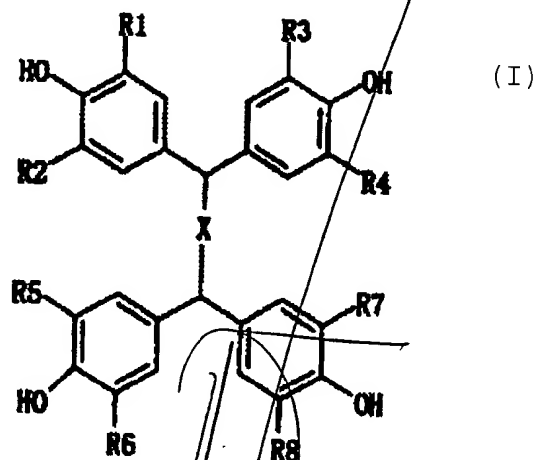


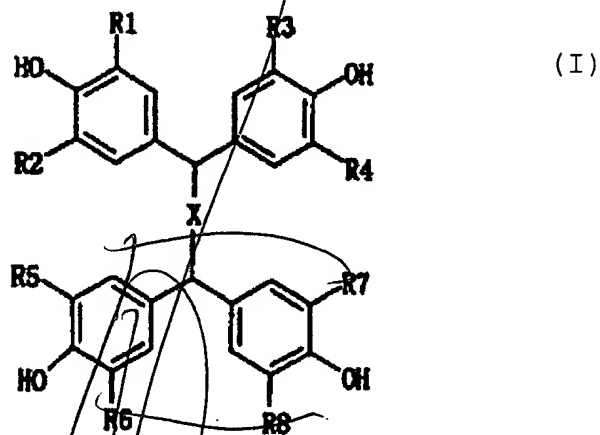
# NEW CLAIMS

6. Epoxy resin compositions characterized by containing a curative which reacts with the epoxy group of an epoxy resin to cure the resin and a tetrakisphenol compound represented by a general formula (I):



wherein X represents  $(CH_2)_n$ , n is 0, 1, 2, or 3, and  $R^1$  to  $R^6$  each represents hydrogen, a lower alkyl, optionally-substituted phenyl, halogeno or a lower alkoxy, in an amount of from 0.001 to 0.1 mole based on 1 mole of the epoxy groups.

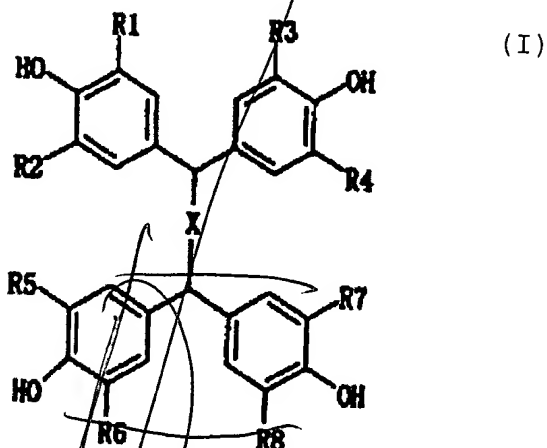
7. Curatives for epoxy resins characterized by being a clathrate comprising a tetrakisphenol compound represented by a general formula (I):



wherein X represents  $(CH_2)_n$ , n is 0, 1, 2, or 3, and  $R^1$  to  $R^8$  each represents hydrogen, a lower alkyl, optionally-substituted phenyl, halogeno or a lower alkoxy; and

a compound which reacts with the epoxy group of an epoxy resin to cure the resin.

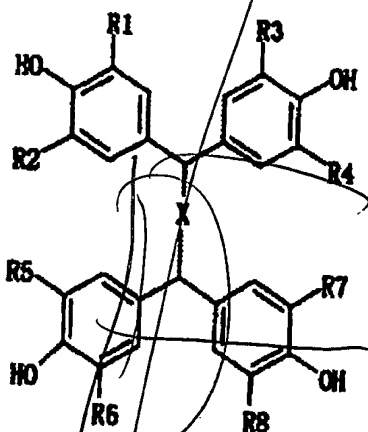
8. A curing accelerator for epoxy resins characterized by being a clathrate comprising a tetrakisphenol compound represented by a general formula (I):



wherein X represents  $(CH_2)_n$ , n is 0, 1, 2, or 3, and  $R^1$  to  $R^8$  each represents hydrogen, a lower alkyl, optionally-substituted phenyl, halogeno or a lower alkoxy; and

a compound accelerating the curing of a compound which reacts with the epoxy group of an epoxy resin to cure the resin.

9. A clathrate curing accelerator for epoxy resins comprising:  
 a tetrakisphenol compound represented by a general formula (I):

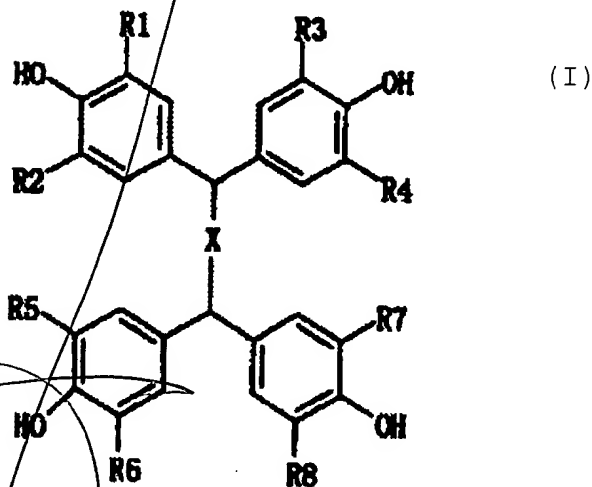


(I)

wherein X represents  $(CH_2)_n$ , n is 0, 1, 2, or 3, and  $R^1$  to  $R^8$  each represents hydrogen, a lower alkyl, optionally-substituted phenyl, halogeno or a lower alkoxy; and

a compound other than the tetrakisphenol compound, which accelerates the curing of an epoxy resin, wherein the clathrate is present in the resin in a range of from 0.001 to 0.1 mole based on 1 mole of the epoxy groups.

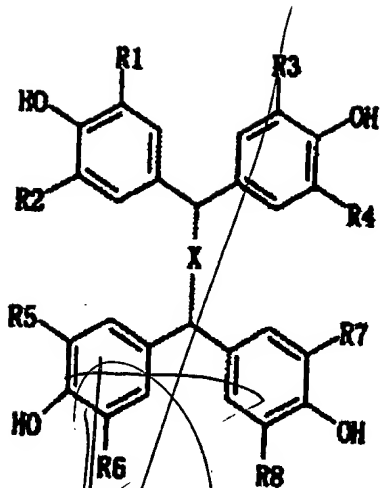
10. Epoxy resin compositions comprising:  
 an epoxy resin, said epoxy resin containing a clathrate  
 curative, said clathrate curative being a tetrakisphenol compound  
 represented by a general formula (I):



wherein X represents  $(CH_2)_n$ , n is 0, 1, 2, or 3, and  $R^1$  to  $R^8$   
 each represents hydrogen, a lower alkyl, optionally-substituted  
 phenyl, halogen or a lower alkoxy; and

a compound other than the tetrakisphenol compound, which  
 reacts with epoxy groups of the epoxy resin to cure the resin,  
 wherein the clathrate curative is present in the resin in a range  
 of from 0.001 to 0.1 mole based on 1 mole of the epoxy groups;  
 and/or

a clathrate curing accelerator, said clathrate curing  
 accelerator being a tetrakisphenol compound represented by a  
 general formula (I):



(I)

wherein  $X$  represents  $(CH_2)_n$ , wherein  $n$  is 0, 1, 2, or 3, and  $R^1$  to  $R^8$  each represents hydrogen, a lower alkyl, optionally-substituted phenyl, halogeno or a lower alkoxy; and

a compound other than the tetrakisphenol compound, which accelerates the curing of an epoxy resin, wherein the clathrate is present in the resin in a range of from 0.001 to 0.1 mole based on 1 mole of the epoxy groups.